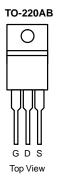
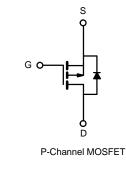


P-Channel 60 V (D-S) MOSFET

PRODUCT	SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)
- 60	0.0480 at V _{GS} = - 10 V	- 45	67
- 30	0.0560 at V_{GS} = - 4.5 V	- 40	07





FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Power Switch
- Load Switch in High Current Applications
- DC/DC Converters

ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless oth	erwise noted)			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 25 °C	I _D	- 45		
	T _C = 70 °C	טי	- 39	А	
Pulsed Drain Current (t = 300 µs)		I _{DM}	- 100		
Avalanche Current		I _{AS}	- 32		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	51	mJ	
Maria David Diaria di ad	T _C = 25 °C	Р	41.7 ^b	14/	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	2.1	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W
Junction-to-Case (Drain)	R _{thJC}	3	0/00

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS (T _J = 25 Parameter	Symbol	Test Conditions	Min.	Typ	Max.	Unit
	Symbol	Test Conditions	MIN.	Тур.	wax.	Unit
Static		<u> </u>				[
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$	- 60			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$	- 1.0		- 3.0	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	μA
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 \text{ °C}$			- 250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 10 V, V_{GS} = - 10 V	- 30			А
	P	V _{GS} = - 10 V, I _D = - 14 A		0.048		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.056		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		40		S
Dynamic ^b		·				
Input Capacitance	C _{iss}			2065		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 30 V, f = 1 MHz		330		
Reverse Transfer Capacitance	C _{rss}			280		
Total Gate Charge ^c	Qg			67	100	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -14 \text{ A}$		13.5		nC
Gate-Drain Charge ^c	Q _{gd}			14		
Gate Resistance	R _g	f = 1 MHz	0.5	2.5	5	Ω
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 2 Ω		11	20	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_{D} \cong$ - 10 A, V_{GEN} = - 10 V, R_{g} = 1 Ω		42	63	
Fall Time ^c	t _f			12	20	
Drain-Source Body Diode Ratings a	nd Characteri	stics T _C = 25 °C ^b				
Continuous Current	۱ _S				- 40	۸
Pulsed Current	I _{SM}				- 100	A
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V
Reverse Recovery Time	t _{rr}			38	57	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dI/dt = 100 A/μs		2.3	3.5	А
Reverse Recovery Charge	Q _{rr}] [40	60	nC

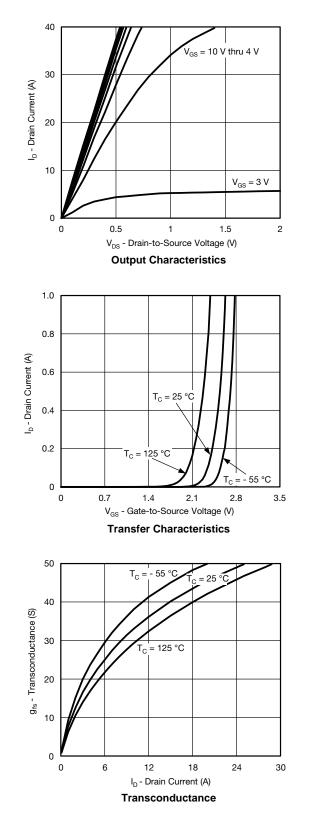
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

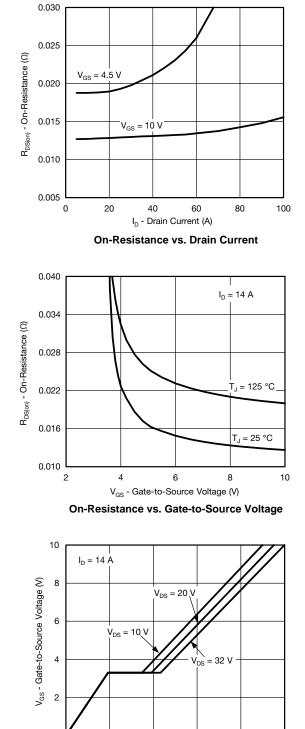
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



14 28 42 56 Q_g - Total Gate Charge (nC) Gate Charge

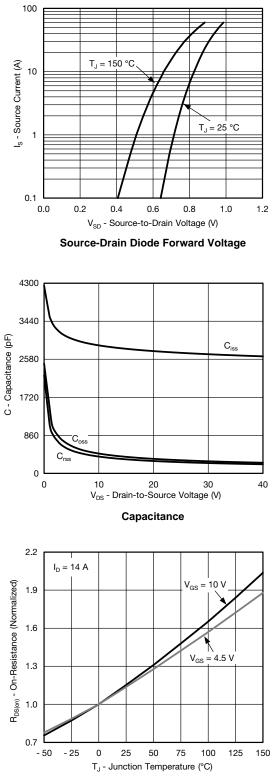
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0

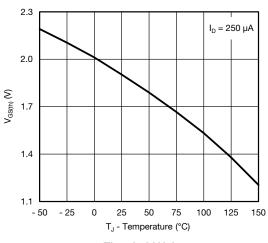
70



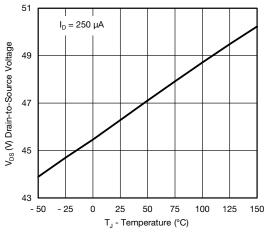




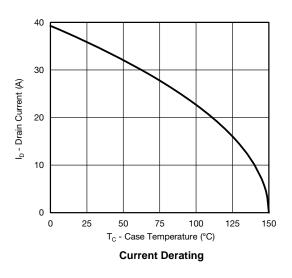
On-Resistance vs. Junction Temperature



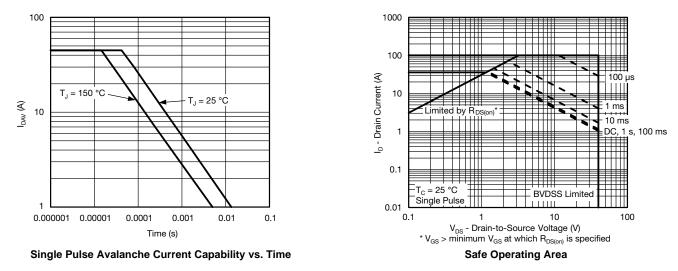
Threshold Voltage



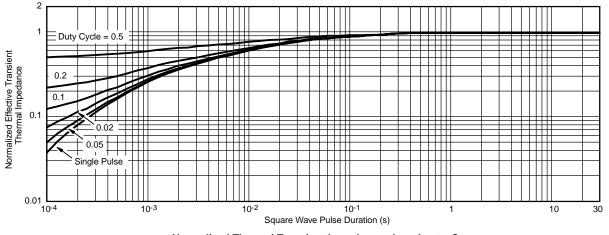
Drain Source Breakdown vs. Junction Temperature







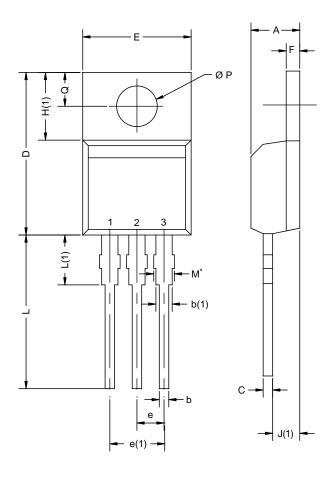
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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